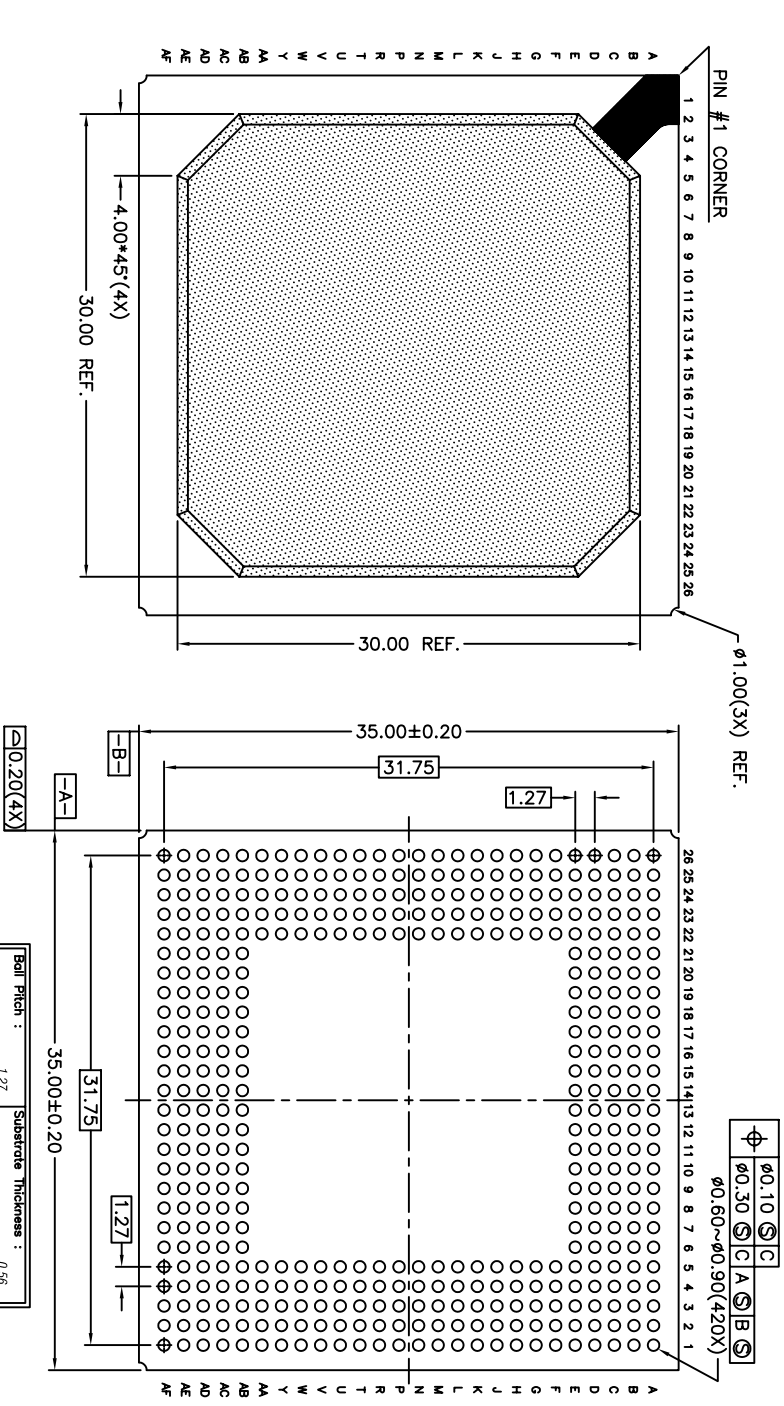


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	07/10/09	P.PAIK
01	COMBINE POD & LAND PATTERN	06/07/13	KS

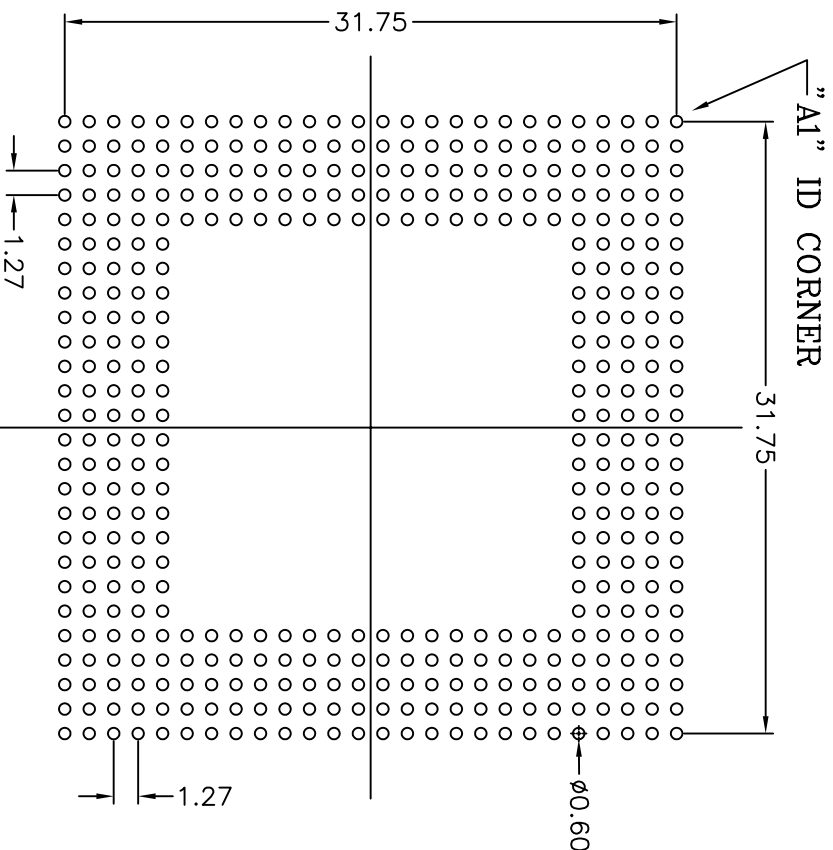


Ball Pitch :	1.27	Substrate Thickness :	0.56
Ball Diameter :	0.75	Mold Thickness :	1.17

TOLERANCES UNLESS SPECIFIED			
DECIMAL	ANGULAR	±1°	
XX±.105			
XXX±.030			
APPROVALS	DATE	TITLE	SIZE
DRAWN 06/09	7/10/09	BG/420 PACKAGE OUTLINE	35 x 35 mm BODY
CHECKED		1.27 mm PITCH PBGA	1.27 mm PITCH PBGA
REV	REV	DO NOT SCALE DRAWING	SHEET 1 OF 2
C	PSC-4271		01

IDT
 6024 SILVER CREEK
 VALLEY ROAD, SAN JOSE,
 CA 95138
 PHONE: (408) 284-8200
 FAX: (408) 284-3572
 WWW.IDT.COM

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	07/10/09	P.PAIK
01	COMBINE POD & LAND PATTERN	06/07/13	KS



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		6024 SILVER CREEK VALLEY ROAD, SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572	
DECIMAL	ANGULAR	 www.IDT.com	
X± .105	±1°		
XX± .050		TITLE BG/BGG 420 PACKAGE OUTLINE 35 x 35 mm BODY 1.27 mm PITCH PBGA	
XXX± .030			
APPROVALS	DATE	SIZE DRAWING No. C PSC-4271	
DRAWN 06/09	7/10/09		
CHECKED		DO NOT SCALE DRAWING	
		SHEET 2 OF 2	